

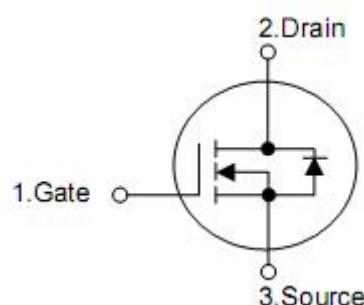
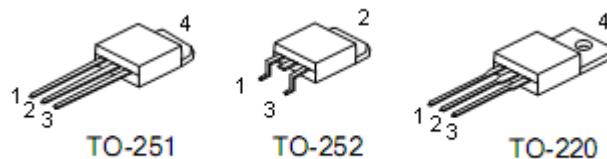
1. Features

- $R_{DS(on)}=10.5\text{m}\Omega$ @ $V_{GS}=10\text{V}$
- Lead free and green device available
- Low Rds-on to minimize conductive loss
- High avalanche current

2. Applications

- Power supply
- UPS
- Battery management system

3. Symbol



Pin	Function
1	Gate
2	Drain
3	Source
4	Drain

4. Absolute maximum ratings

($T_A=25^\circ\text{C}$,unless otherwise noted)

Parameter		Symbol	Rating	Units
Drain-source voltage		V_{DSS}	60	V
Gate-source voltage		V_{GSS}	+25	V
Continuous drain current	$T_C=25^\circ\text{C}$	I_D^3	50	A
	$T_C=100^\circ\text{C}$		35	A
Pulse drain current	$T_C=25^\circ\text{C}$	I_{DP}^4	250	A
Avalanche current		I_{AS}^5	15	A
Avalanche energy,		E_{AS}^5	120	mJ
Maximum power dissipation	$T_C=25^\circ\text{C}$	P_D	88	W
	$T_C=100^\circ\text{C}$		44	W
Junction & storage temperature range		T_J, T_{STG}	-55-175	°C

5. Thermal characteristics

Parameter	Symbol	Rating		Unit
		To-252/ 251	To-220	
Thermal resistance,Junction-ambient	$R_{\theta JA}$	100	62.5	°C/W
Thermal resistance,Junction-case	$R_{\theta JC}$	1.1	1.7	°C/W

6. Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=250\mu\text{A}$	60	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$T_J=125^\circ\text{C}$	-	-	20	
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	3.0	4.0	V
Gate leakage current	I_{GSS}	$V_{\text{GS}}=\pm 25\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Drain-source on-resistance	$R_{\text{DS(on)}}^1$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	-	10.5	12.5	$\text{m}\Omega$
Gate resistance	R_g	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	1.0	-	Ω
Diode forward voltage	V_{SD}^1	$I_{\text{SD}}=30\text{A}, V_{\text{GS}}=0\text{V}$	-	0.8	1.3	V
Diode continuous forward current	I_S^3		-	-	50	A
Reverse recovery time	t_{rr}	$I_F=30\text{A},$ $dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	-	32	-	nS
Reverse recovery charge	Q_{rr}		-	60	-	nC
Input capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V},$ $f=1\text{MHz}$	-	2060	-	pF
Output capacitance	C_{oss}		-	755	-	
Reverse transfer capacitance	C_{rss}		-	375	-	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=30\text{A},$ $R_G=5\Omega, V_{\text{GS}}=10\text{V}$	-	14	-	nS
Rise time	t_r		-	13	-	
Turn-off delay time	$t_{\text{d(off)}}$		-	20	-	
Fall time	t_f		-	7.5	-	
Total gate charge	Q_g	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=10\text{V}$ $I_{\text{DS}}=30\text{A}$	-	50	-	nC
Gate-source charge	Q_{gs}		-	12	--	
Gate-drain charge	Q_{gd}		-	17	--	

Note:1: Pulse test; pulse width $\leq 300\text{us}$ duty cycle $\leq 2\%$.

2: Guaranteed by design, not subject to production testing.

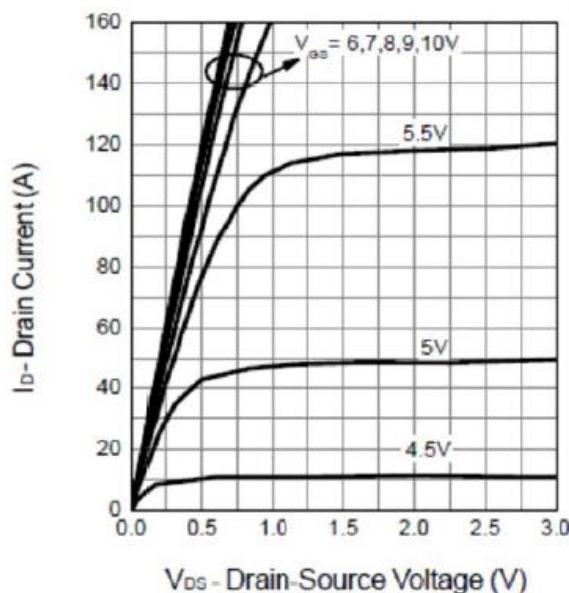
3: Package limitation current is 50A.Calculated continuous current based on maximum allowable junction temperature.

4: Repetitive rating, pulse width limited by max junction temperature.

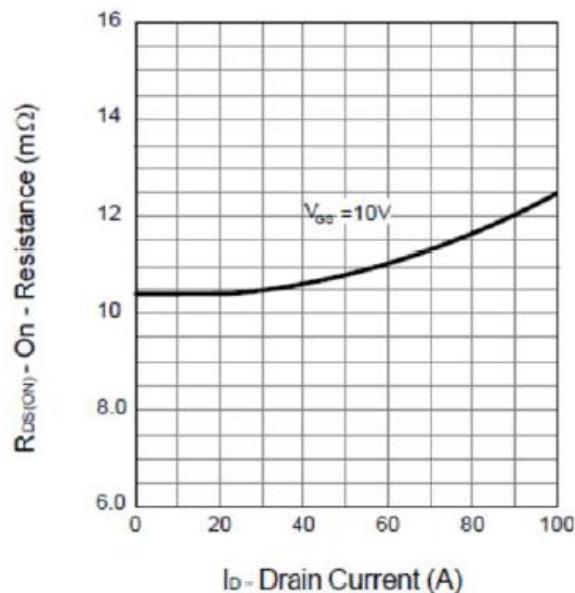
5: Starting $T_J=25^\circ\text{C}, L=0.5\text{mH}, I_{\text{AS}}=31\text{A}$.

7. Test circuits and waveforms

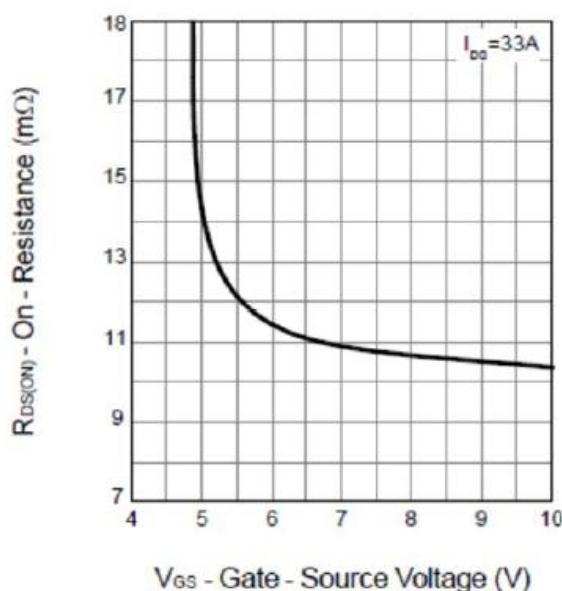
Output Characteristics



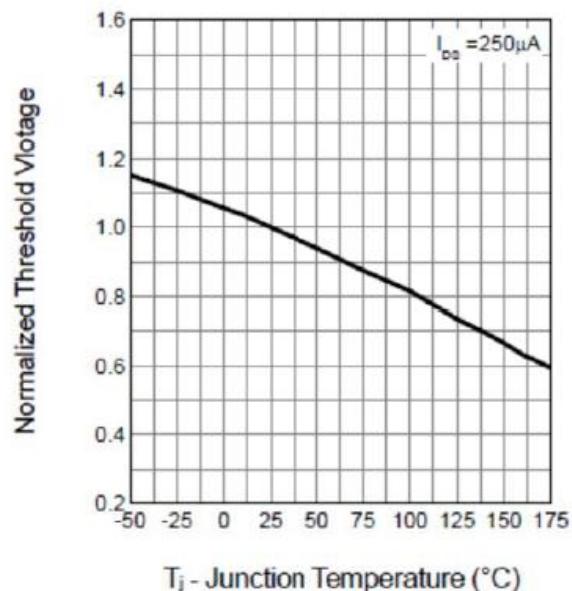
Drain-Source On Resistance

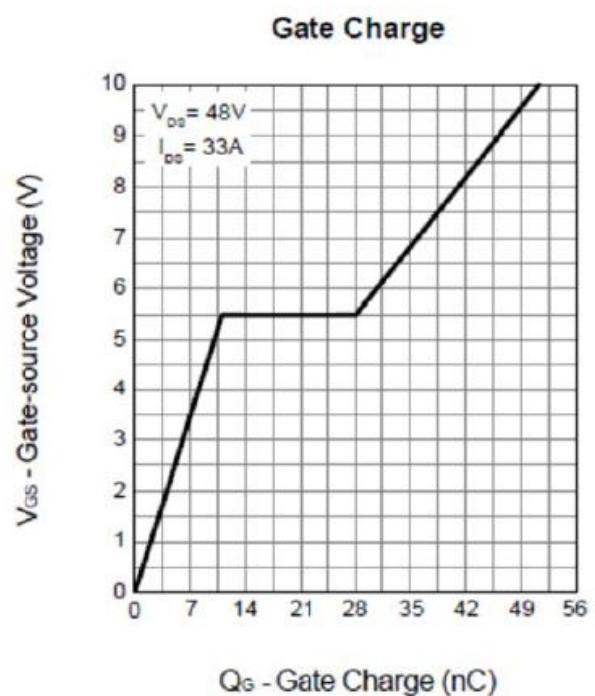
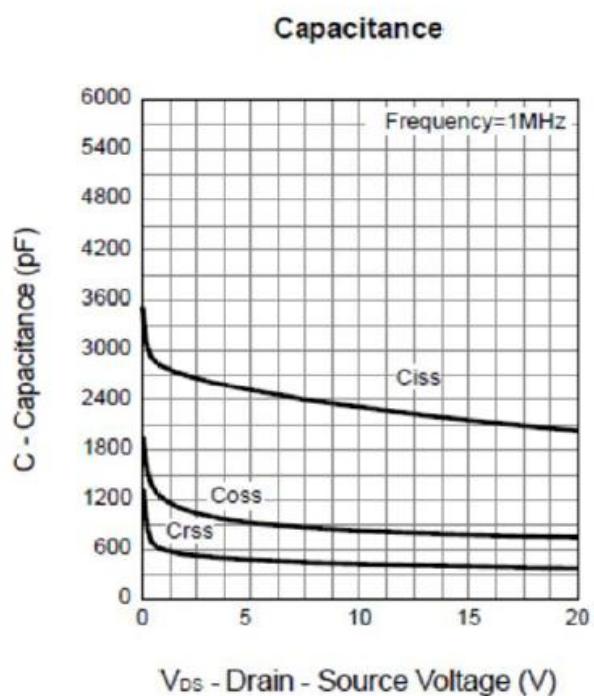
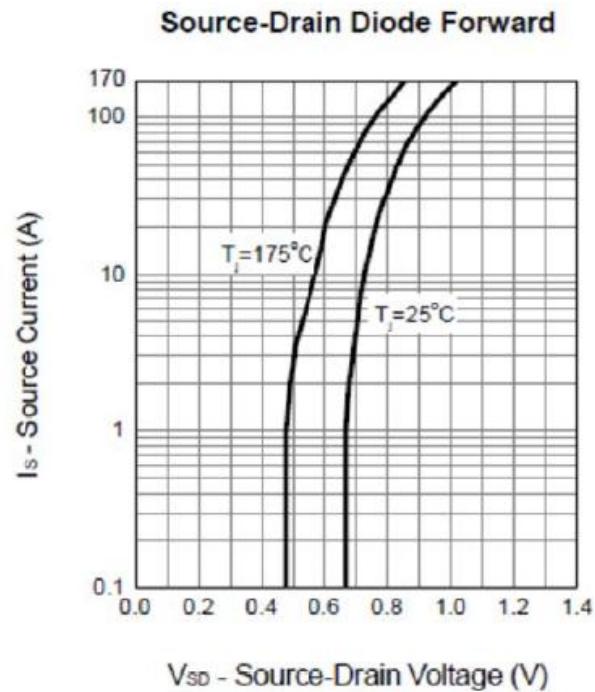
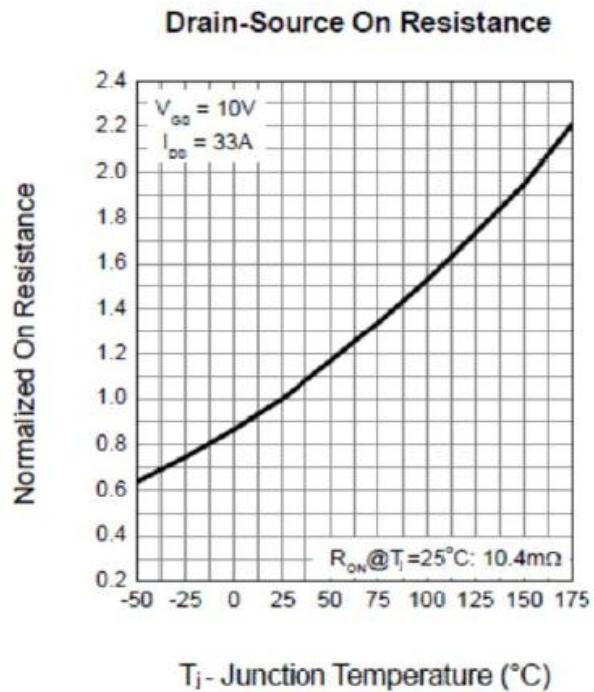


Drain-Source On Resistance

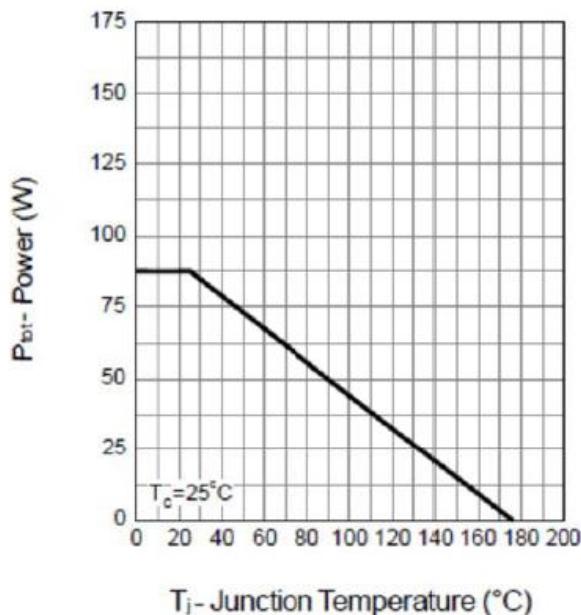


Gate Threshold Voltage

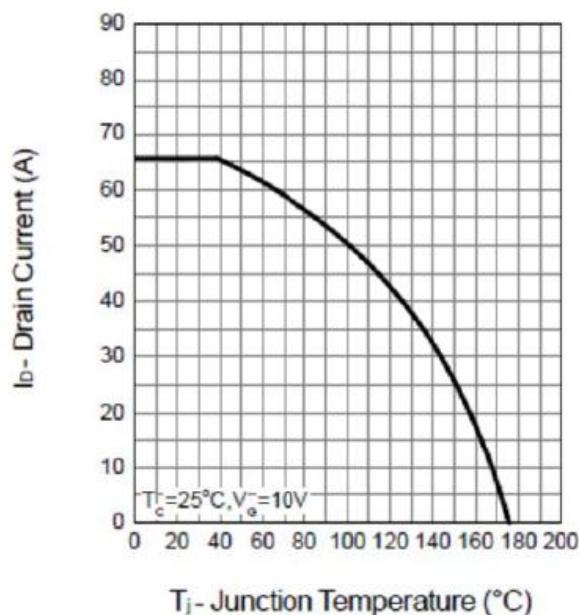




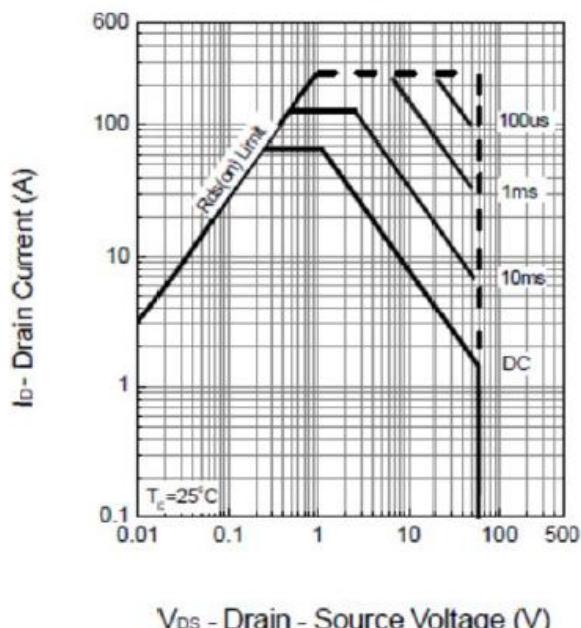
Power Dissipation



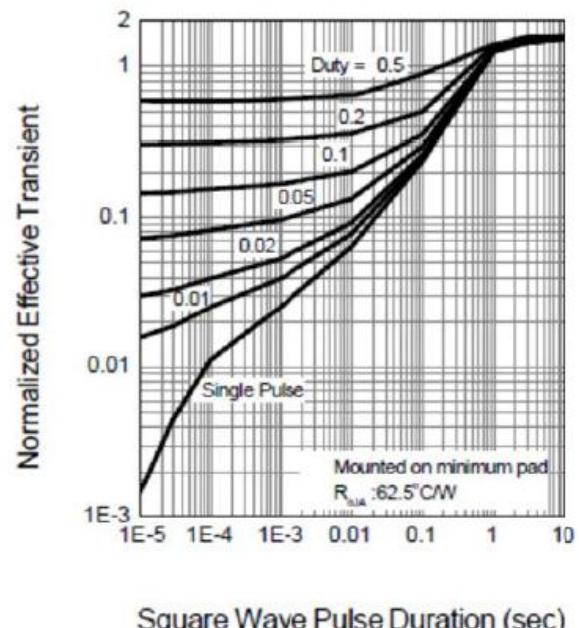
Drain Current



Safe Operation Area



Thermal Transient Impedance



V_{DS} - Drain - Source Voltage (V)

Square Wave Pulse Duration (sec)